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**Sputtering Au on Si using Sputter#4**

**Sputtering Condition:** 5mT, 200W, Ar=45sccm, z=1, tilting=10, and time=120 s

Result: the sputtering rate≈17.7nm/min, roughness Ra= 0.430 nm.

Figure 1 Film Thickness=35.3nm.
Figure 2 Surface scan by AFM (Ra=0.430 nm)